

RECORI U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office 101406806 To the Honorable Commissioner of Patents and Trac. 1. Name of conveying party(les) APR -3 AM II: 29 2. Name and address of receiving party(ies) SONY CORPORATION Harumi KAWAMURA, Mari HURTUUCHE Name: 7-35 Kitashinagawa 6-chome Shinagawa-Ku, Tokyo 100-31, Japan Additional name(s) of conveying party(ies) attached? Additional name(s) & address(es) attached? Yes x No ___ Yes <u>X</u> No mRA 3. Nature of conveyance: 4.3.00 X Assignment Security Agreement __ Merger Change of Name X Other (1. 5.5.N. 09) 46.3, 798 Execution Date: February 7, 2000 Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: Int'l Patent Application No.(s) PCT/JP99/02852 (USSN) filed 28 May 1999 Additional numbers attached? __ Yes _X No 6. Total number of applications and 5. Name and address of party to whom correspondence concerning document should be mailed: 1 WILLIAM S. FROMMER \$ 40.00 Enclosed <u>X</u> Internal Address: FROMMER LAWRENCE & HAUG LLP Authorized to be charged to deposit account 50-0320 Street Address: 745 FIFTH AVENUE 8. Deposit account number: NEW YORK State: N.Y. Zip: 10151 City: (Attach duplicate copy of this page if paying by deposit account) Do not use this space Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. March 29, 2000 GLENN F. SAVIT Name of Person Signing Total number of pages including cover sheet, attachments, and document: 2 Do not detach this portion Mail documents to be recorded with required cover sheet information to: Commissioner of Patents and Trademarks 05/b1/2000 TTON11 00000172 PCTJP9902852 Box Assignments 40.00 DP Washington, D.C. 20231 FC:581 Public burden reporting for this sample cover sheet is estimated to average about 30 minutes per document to be recorded,

including time for reviewing the document and gathering the data needed, and completing and reviewing the sample cover sheet. Send comments regarding this burden estimate to the U.S. Patent and Trademark Office, Office of Information Systems, PK2-1000C, Washington, D.C. 20231, and to the Office of Management and Budget, Paperwork Reduction Project (0651-0011), Washington, D.C. 20503.

PATENT REEL: 010914 FRAME: 0667

19-15551180.

FLH File No. 450104-4896

ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and

INFORMATION PROCESSING APPARATUS, INFORMATION PROCESSING SYSTEM, INFORMATION PROCESSING METHOD, AND PROVIDING MEDIUM for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address:

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo 141, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

| inis assignment executed on the dates indicated below. | | |
|--|---|---|
| Harumi KAWAMURA | | |
| Name of first or sole inventor | Execution date of U.S. Patent Application | |
| Tokyo, Japan | | |
| Residence of first or sole inventor (Samm Kanamura | Feb. 7, 2000 | |
| Signature of first or sole inventor | Date of this assignment | |
| Mari HORIGUCHI | | |
| Name of second inventor | Execution date of U.S. Patent Application | |
| Kanagawa, Japan | | |
| Residence of second inventor Mari Horzynchi | Feb 7, 2000 | , |
| Signature of second inventor | Date of this assignment | |
| Name of third inventor | Execution date of U.S. Patent Application | |
| Residence of third inventor | | |
| Signature of third inventor | Date of this assignment | |

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RECORDED: 04/03/2000